

Appl. No. 10/823,098
Amdt. dated 04/11/2008
Reply to Office action of 03/20/2008

Amendment of the Abstract

Please replace the current abstract with the following new abstract:

By thermally contacting a coil (located within a micro-structure) with a heat diffuser, that is thermally connected to the substrate through a thermally conductive pedestal, efficient transfer of heat from the coil to the substrate is facilitated.